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Title of Change:	Bare Cu wire to Pd-coated Cu wire conversion; And Nitto GE200 to Henkel GR640 molding compour conversion for transistor devices assembled in ON Semi Leshan facility.	
Proposed Changed Material First Ship Date:	21 May 2021 or earlier if approved by customer	
Current Material Last Order Date:	28 Feb 2021 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
Current Material Last Delivery Date:	20 May 2021 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory	
Product Category:	Active components – Discrete components	
Contact information:	Contact your local ON Semiconductor Sales Office or Andy.Tao@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <u>PCN.samples@onsemi.com</u> Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	22 Jun 2020	
PPAP Availability Date:	20 Jun 2020	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or ffvf9f@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.	
Change Category	•	
Category	Type of Change	
Process - Assembly	Change of mold compound,	

Description and Purpose:

Process - Assembly

Upon the expiration of this PCN, these devices will be built with 0.8 mils Pd-coated Cu wire & Henkel GR640 HV mold compound at the same site.

Datasheet specifications and product electrical performance remain unchanged.

Reliability qualification and full electrical characterization over temperature has been performed.

Change of wire bonding

	Before Change Description After Change Description		
Bond Wire	0.8 mils bare Cu wire	0.8 mils Pd-coated Cu wire	
Mold compound	Hitach GE200F	Henkel GR640 HV	

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Reason / Motivation for Change: Process/Materials Change						
inction, relial	pact on fit, form, bility, product ıfacturability:	The device has been qualified and validated based on the same Product Specification. The device h successfully passed the qualification tests. Potential impacts can be identified, but due to testi performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.				
ites Affected:						
N Semicondu	ictor Sites		External Foundry/Subco	on Sites		
shan Phoenix	Semiconductor, China		None			
larking of Pai hange:	rts/ Traceability of		ts assembled with 0.8mils Pd-coated Cu wire & Henkel GR640 HV mold compound from onductor Leshan facility will have a Finish Goods Date Code of WW17, 2021or later.			
QV DEVICE RMS PACKAGE	NAME: <u>SMUN5211DW:</u> : <u>40517</u> : <u>SC88</u>	<u>1T16</u>				
Test	Specification		Condition	Interval	Results	
HTRB	JESD22-A108	Ta=150°C, 100% r		2016hrs	0/231	
HTSL	JESD22-A103	Ta= 150°C		2016 hrs	0/231	
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj On/off = 2 min	i=100°C	30К сус	0/231	
TC	JESD22-A104	Ta= -65°C to +150	°C	2000 cyc	0/231	
HAST	JESD22-A110	130°C, 85% RH, 18	3.8psig, bias	192hrs	0/231	
uHAST	JESD22-A118	130°C, 85% RH, 18	3.8psig, unbiased	96 hrs	0/231	
PC	J-STD-020 JESD-A	113	MSL 1 @ 260 °C		0/924	
RSH	JESD22- B106		Ta = 265C, 10 sec	-	0/30	
-	AME: <u>SBC846BDW1T10</u>	<u>3</u>				
RMS PACKAGE	: <u>40518</u> : <u>SC88</u>					
			Condition	Interval	Results	
PACKAGE	: <u>SC88</u>	Ta=150°C, 100%		Interval 2016hrs	Results 0/231	
PACKAGE Test	: <u>SC88</u> Specification JESD22-A108 JESD22-A103	Ta= 150°C				
PACKAGE Test HTRB	: <u>SC88</u> Specification JESD22-A108	Ta= 150°C	max rated V	2016hrs	0/231	
PACKAGE Test HTRB HTSL	: <u>SC88</u> <u>Specification</u> JESD22-A108 JESD22-A103 MIL-STD-750 (M1037)	Ta= 150°C Ta=+25°C, delta T On/off = 2 min	max rated V :j=100°C	2016hrs 2016 hrs	0/231 0/231	
PACKAGE Test HTRB HTSL IOL	: <u>SC88</u> <u>Specification</u> JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101	Ta= 150°C Ta=+25°C, delta T On/off = 2 min Ta= -65°C to +150	max rated V ;j=100°C)°C	2016hrs 2016 hrs 30K cyc	0/231 0/231 0/231 0/231 0/231	
PACKAGE Test HTRB HTSL IOL TC	: <u>SC88</u> <u>Specification</u> JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104 JESD22-A110 JESD22-A118	Ta= 150°C Ta=+25°C, delta T On/off = 2 min Ta= -65°C to +150 130°C, 85% RH, 1 130°C, 85% RH, 1	max rated V ;j=100°C 9°C 8.8psig, bias	2016hrs 2016 hrs 30K cyc 2000 cyc	0/231 0/231 0/231 0/231	
PACKAGE Test HTRB HTSL IOL TC HAST	: <u>SC88</u> <u>Specification</u> JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104 JESD22-A110	Ta= 150°C Ta=+25°C, delta T On/off = 2 min Ta= -65°C to +150 130°C, 85% RH, 1 130°C, 85% RH, 1	max rated V ;j=100°C 9°C 8.8psig, bias	2016hrs 2016 hrs 30K cyc 2000 cyc 192hrs	0/231 0/231 0/231 0/231 0/231 0/231	



QV DEVICE NAME: <u>BC856BDW1T1G</u> RMSvvv : <u>40519</u> PACKAGE : <u>SC88</u>				
Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	2016hrs	0/231
HTSL	JESD22-A103	Ta= 150°C	2016 hrs	0/231
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	30К сус	0/231
TC	JESD22-A104	Ta= -65°C to +150°C	2000 cyc	0/231
H3TRB	JEDS22 A101	85°C, 85% RH, V=80% rated V or 100V max. 2016 Hours	2016hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-	0/924
RSH	JESD22- B106	Ta = 265C, 10 sec	-	0/30

Note: AEC-1pager is attached.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer

2. Open the downloaded pdf copy of the PCN

3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field

4. Then click on the attached file/s

Electrical Characteristics Summary:

Three temperature characterization and ESD performance meet datasheet specification. Detail of electrical characterization result is available upon request.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle		
NSVMUN5135DW1T1G	N/A	SMUN5211DW1T1G		
NSVMUN5211DW1T2G	N/A	SMUN5211DW1T1G		
NSVMUN5233DW1T3G	N/A	SBC846BDW1T1G		
NSVMUN5333DW1T3G	N/A	SBC846BDW1T1G,BC856BDW1T1G		
NSVT65010MW6T1G	N/A	BC856BDW1T1G		
NSVT65011MW6T1G	N/A	SBC846BDW1T1G		
NSVUMZ1NT1G	N/A	SBC846BDW1T1G,BC856BDW1T1G		



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NSVMUN5211DW1T2G		SMUN5211DW1T1G		
NSVT65010MW6T1G		BC856BDW1T1G		
NSVT65011MW6T1G		SBC846BDW1T1G		
NSVMUN5135DW1T1G		SMUN5211DW1T1G		